

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 2002-261204
 (43)Date of publication of application : 13.09.2002

(51)Int.Cl. H01L 23/32

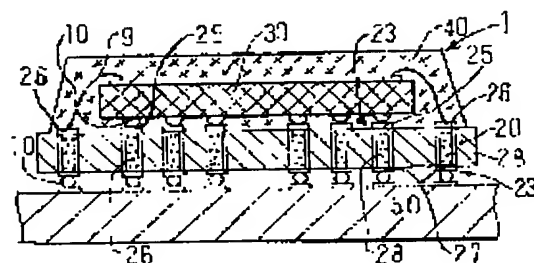
(21)Application number : 2001-057809 (71)Applicant : HITACHI AIC INC
 (22)Date of filing : 02.03.2001 (72)Inventor : ISHIKAWA KAZUMITSU
 EZUKA MASAHIRO
 SAKURAI MASAYUKI

(54) INTERPOSER BOARD AND ELECTRONIC COMPONENT BODY HAVING THE SAME

(57)Abstract:

PROBLEM TO BE SOLVED: To realize high quality for an interposer board and an electronic component body other than the miniaturization and narrow pitch of an electrode pad and connection land.

SOLUTION: In an interposer board, the surface of a blind conduction body is used as an electrode pad or a land for connection, which is formed by forming plating layers on both end faces of a filler which is filled inside via holes piercing a printed wiring board, so as to be the same planarity as both surfaces of the printed wiring board.



LEGAL STATUS

[Date of request for examination] 21.01.2002
 [Date of sending the examiner's decision of rejection] 11.05.2006
 [Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]
 [Date of final disposal for application]
 [Patent number]
 [Date of registration]
 [Number of appeal against examiner's decision of rejection]
 [Date of requesting appeal against examiner's decision of rejection]
 [Date of extinction of right]